

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity.

Please amend the claims as follows:

9. (Twice Amended) A device for establishing electrical contact with a lead element extending from an IC device, comprising:
a substantially planar substrate bounded by a first substantially planar surface and an opposing, second substantially planar surface and having at least one conductive trace;
a spring contact including a base portion and a contact portion, said contact portion comprising a resiliently compressible coil spring configured to bias against and electrically contact said lead element of said IC device; and
an aperture including a seat portion opening onto said first substantially planar surface of said substantially planar substrate and a retaining portion having a first end connected to an opposing end of said seat portion and a second end extending a depth at least partially into said substantially planar substrate, said seat portion of said aperture configured to at least partially contain said contact portion of said spring contact and said retaining portion of said aperture configured to receive and electrically connect said base portion of said spring contact to said at least one conductive trace.

10. (Twice Amended) The device of claim 9, wherein said second end of said retaining portion does not extend entirely through said substantially planar substrate to said opposing, second substantially planar surface.

11. (Amended) The device of claim 9, further comprising a layer of conductive material disposed on at least a portion of an interior wall of said aperture, said layer of conductive material electrically connecting said base portion of said spring contact to said at least one conductive trace.

12. (Amended) The device of claim 11, wherein said at least one conductive trace is formed on said first substantially planar surface of said substantially planar substrate.

13. (Amended) The device of claim 11, wherein said at least one conductive trace is formed within an intermediate conductive plane of said substantially planar substrate.

14. (Twice Amended) The device of claim 11, wherein said retaining portion of said aperture extends through said substantially planar substrate and opens onto said opposing, second substantially planar surface of said substantially planar substrate and said at least one conductive trace is formed on said opposing, second substantially planar surface of said substantially planar substrate.

15. (Previously Amended) The device of claim 9, further comprising a volume of conductive filler material disposed in and filling at least a partial depth of said aperture and electrically contacting said base portion of said spring contact.

16. (Amended) The device of claim 15, wherein said conductive filler material is electrically connected to said at least one conductive trace of said substantially planar substrate.

17. (Amended) The device of claim 16, wherein said at least one conductive trace is formed within an intermediate conductive plane of said substantially planar substrate.

18. (Twice Amended) The device of claim 16, wherein said retaining portion of said aperture extends through said substantially planar substrate and opens onto said opposing, second substantially planar surface of said substantially planar substrate and said at least one conductive trace is formed on said opposing, second substantially planar surface of said substantially planar substrate.

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20. (Twice Amended) The device of claim 9, wherein said second end of said retaining portion opens onto said opposing, second substantially planar surface of said substantially planar substrate.

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21. (Twice Amended) The device of claim 9, wherein said seat portion comprises a generally hemispherical recess formed in said first substantially planar surface of said substantially planar substrate, a generally conical recess formed in said first substantially planar surface of said substantially planar substrate, or a generally cylindrical recess formed in said first substantially planar surface of said substantially planar substrate.

22. (Previously Amended) The device of claim 9, wherein said seat portion is further configured to at least partially align said lead element of said IC device relative to said spring contact.

23. (Previously Amended) The device of claim 9, wherein said contact portion of said spring contact comprises a resiliently compressible coil spring having at least two spring coils for contacting portions thereof and configured to bias against and electrically contact said lead element of said IC device.

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42. The device of claim 9, wherein said resiliently compressible coil spring of said contact portion further comprises at least one point for penetrating an outer surface of said lead element of said IC device.

43. The device of claim 9, wherein said resiliently compressible coil spring of said contact portion further comprises a contact element selected from the group consisting of a sharp edge formed by a cross-section of said resiliently compressible coil spring, a blade extending longitudinally along a surface of said resiliently compressible coil spring, a blade extending circumferentially around a surface of said resiliently compressible coil spring or a barb protruding from a surface of said resiliently compressible coil spring.

circumferentially around a surface of said resiliently compressible coil spring or a barb protruding from a surface of said resiliently compressible coil spring.

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P1 44. (Amended) The device of claim 9, further comprising a clamping element configured to secure said IC device to said first substantially planar surface of said substantially planar substrate.

45. The device of claim 44, wherein said clamping element comprises a stab-in-place clip. *NE*